

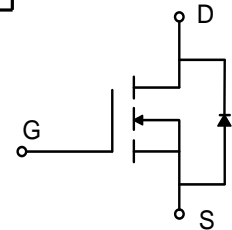
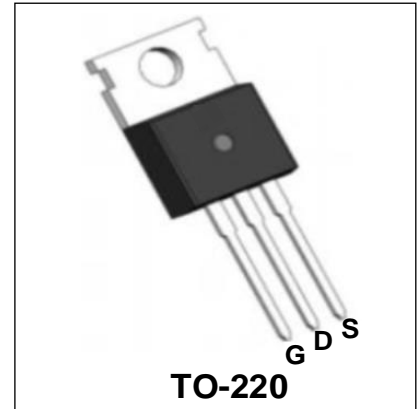
## 40V N-Channel Enhancement Mode Power MOSFET

### Description

WMK80NN04T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 40V$ ,  $I_D = 80A$   
 $R_{DS(on)} < 7m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 12m\Omega$  @  $V_{GS} = 4.5V$
- High Density Cell Design
- Fully Characterized Avalanche Voltage and Current
- Low  $R_{DS(on)}$
- Good Stability and Uniformity with High EAS
- Excellent Package for Good Heat Dissipation



### Applications

- Load Switch
- Uninterruptible Power Supply
- Hard Switched and High Frequency Circuits

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	$T_C = 25^\circ C$	80
		$T_C = 100^\circ C$	55
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	235	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	121	mJ
Avalanche Current	$I_{AS}$	22	A
Total Power Dissipation <sup>4</sup>	$P_D$	56.8	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	2.2	$^\circ C/W$

**Electrical Characteristics** T<sub>c</sub> = 25°C, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	<b>V<sub>(BR)DSS</sub></b>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	40	-	-	V
Gate-body Leakage current	<b>I<sub>GSS</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	<b>I<sub>DSS</sub></b>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-Threshold Voltage	<b>V<sub>GS(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.7	2.5	V
Drain-Source on-Resistance <sup>2</sup>	<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	6	7	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	8.8	12	
Forward Transconductance <sup>2</sup>	<b>g<sub>fs</sub></b>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 15A	-	28	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	<b>C<sub>iss</sub></b>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz	-	2400	-	pF
Output Capacitance	<b>C<sub>oss</sub></b>		-	192	-	
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		-	160	-	
<b>Switching Characteristics</b>						
Gate Resistance	<b>R<sub>g</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	-	1.7	-	Ω
Total Gate Charge	<b>Q<sub>g</sub></b>	V <sub>GS</sub> = 10, V <sub>DS</sub> = 20V, I <sub>D</sub> = 30A	-	44	-	nC
Gate-Source Charge	<b>Q<sub>gs</sub></b>		-	5	-	
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		-	11.5	-	
Turn-on Delay Time	<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 20V, R <sub>G</sub> = 3Ω, R <sub>L</sub> = 1Ω, I <sub>D</sub> = 30A	-	11	-	nS
Rise Time	<b>t<sub>r</sub></b>		-	33	-	
Turn-off Delay Time	<b>t<sub>d(off)</sub></b>		-	42	-	
Fall Time	<b>t<sub>f</sub></b>		-	13	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	<b>V<sub>SD</sub></b>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	<b>I<sub>S</sub></b>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	80	A
Body Diode Reverse Recovery Time	<b>t<sub>rr</sub></b>	I <sub>F</sub> = 20A, dI/dt = 100A/μs	-	13.5	-	nS
Body Diode Reverse Recovery Charge	<b>Q<sub>rr</sub></b>		-	5	-	nC

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=30V, V<sub>GS</sub>=10V, L=0.5mH, I<sub>AS</sub>=22A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

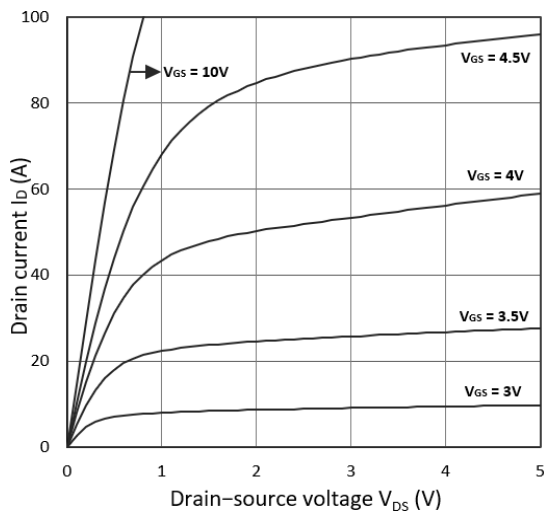


Figure 1. Output Characteristics

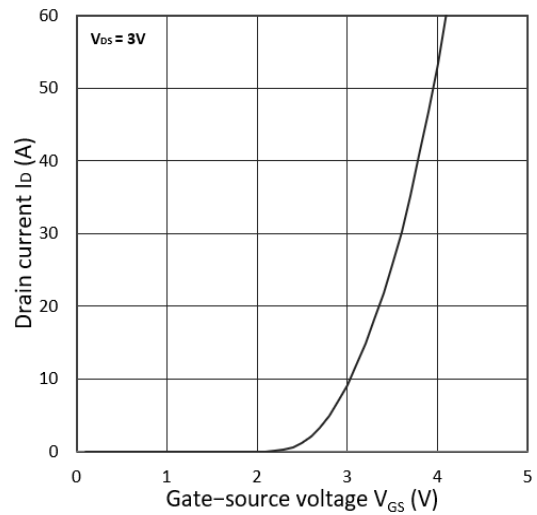


Figure 2. Transfer Characteristics

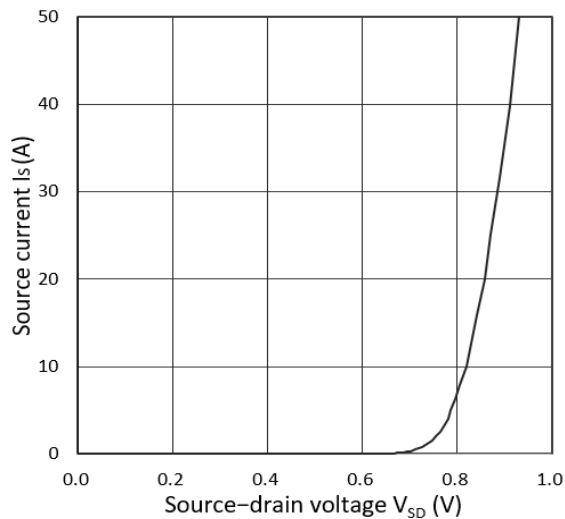


Figure 3. Forward Characteristics of Reverse

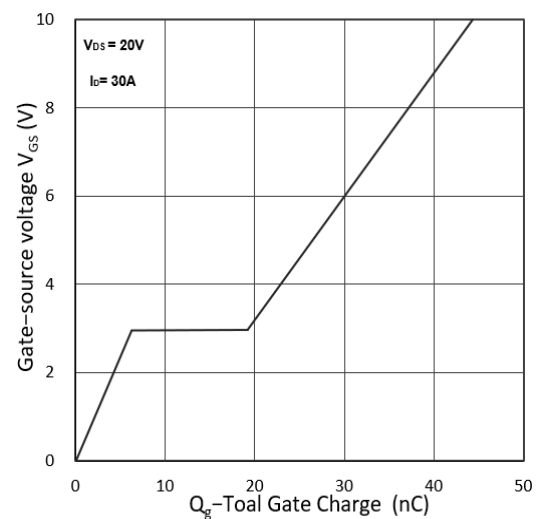


Figure 4. Gate Charge Characteristics

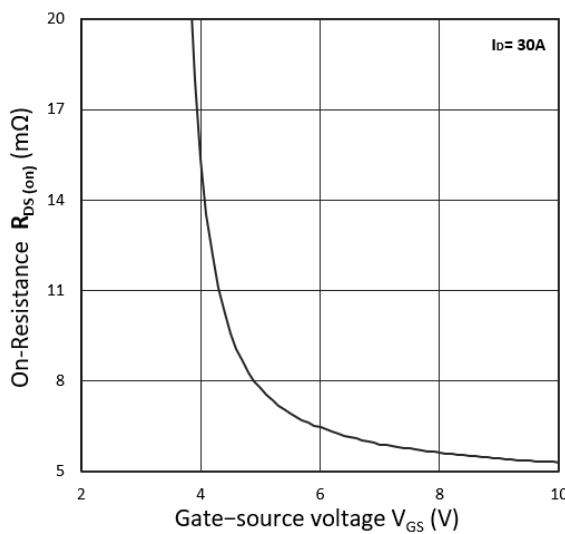


Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$

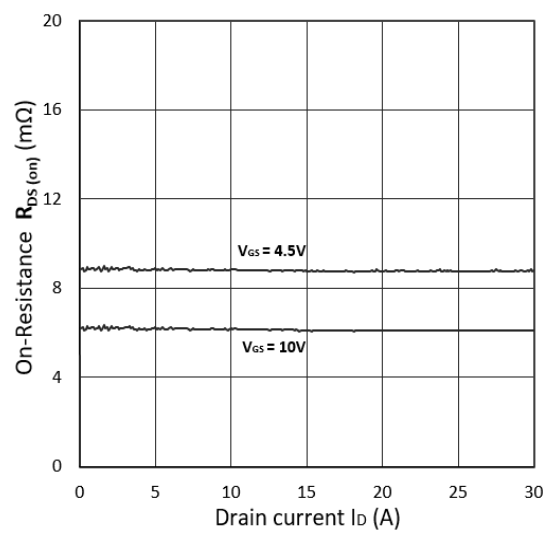


Figure 6.  $R_{DS(on)}$  vs.  $I_D$

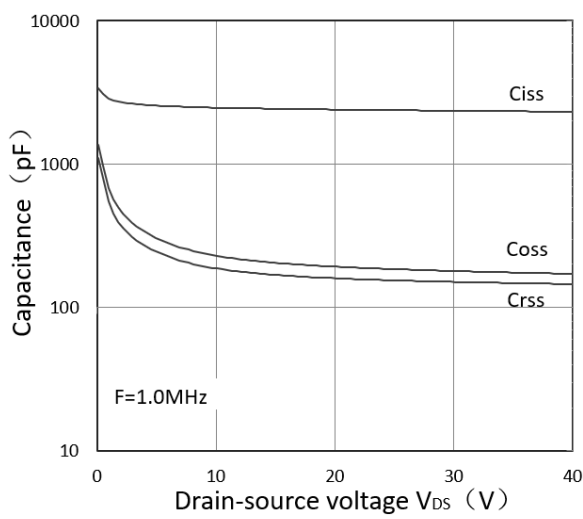


Figure 7. Capacitance Characteristics

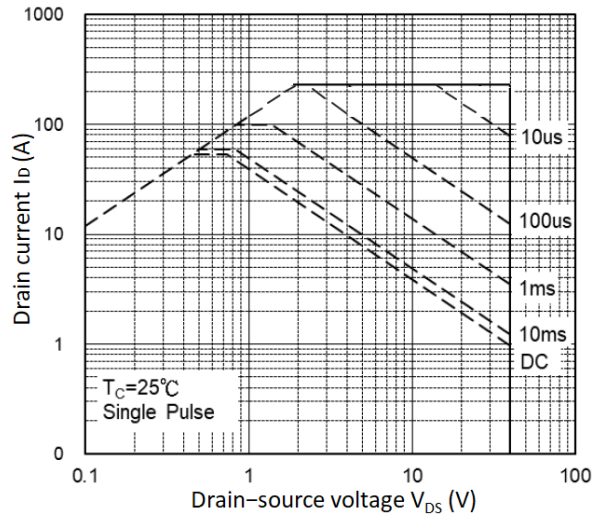


Figure 8. Safe Operating Area

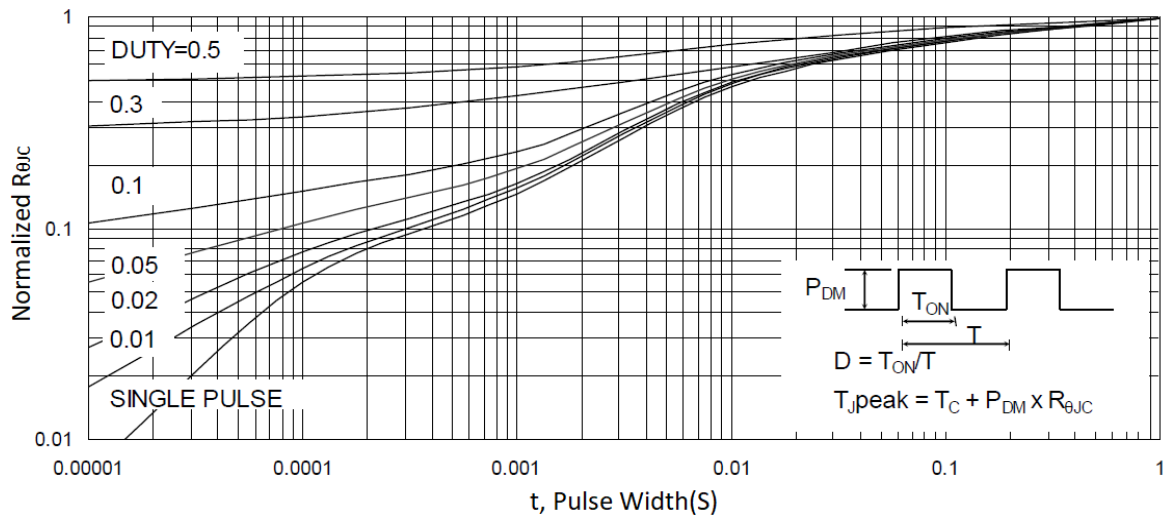


Figure 9. Normalized Maximum Transient Thermal Impedance

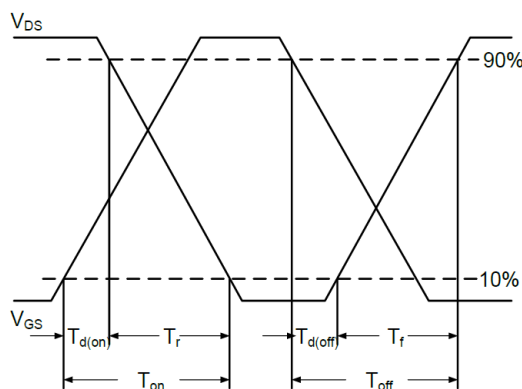


Figure 10. Switching Time Waveform

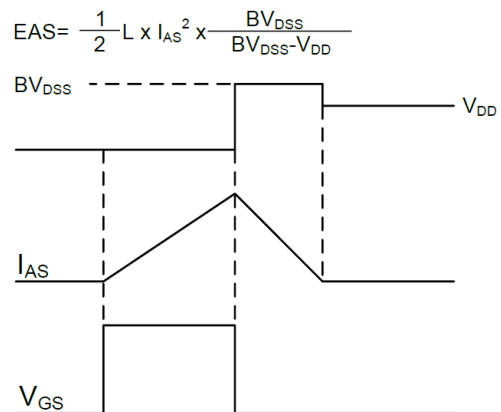
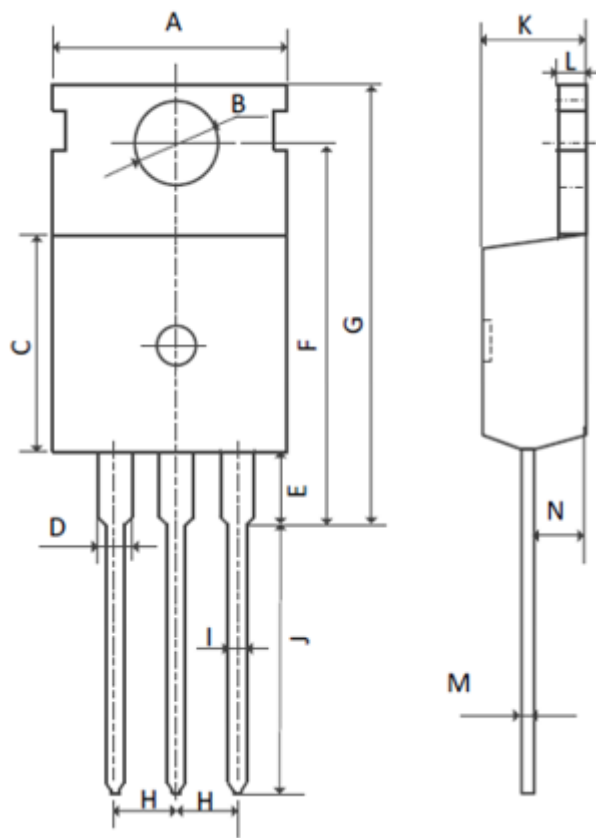


Figure 11. Unclamped Inductive Switching Waveform

Mechanical Dimensions for TO-220



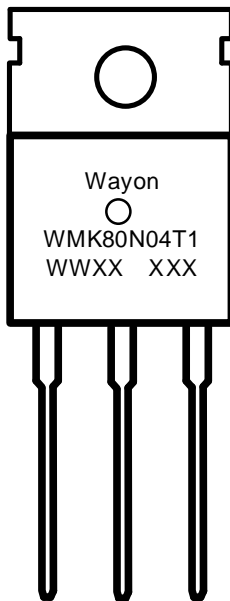
COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.40
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60

## Ordering Information

Part	Package	Marking	Packing method
WMK80N04T1	TO-220	WMK80N04T1	Tube

## Marking Information



WMK80N04T1 = Device code

WWXX XXX= Date code


## Contact Information

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